

ABSTRACT

Embodiments disclosed herein include electronic packages for PoINT architectures. Particularly, embodiments include electronic packages that include reinforcement substrates to minimize warpage. In an embodiment, an electronic package comprises, a reinforcement substrate, a plurality of through substrate vias through the reinforcement substrate, a dielectric substrate over the reinforcement substrate, a cavity into the dielectric substrate, and a component in the cavity.

Fig. 1A